

ABSTRACT OF DISCLOSURE

A stack chip module includes a substrate having a predetermined-size groove on one side and a circuit pattern, one end of the circuit pattern being adjacent to the groove; a first semiconductor chip adhered in the groove of the substrate by adhesive and having a plurality of center pads and a plurality of edge pads, electrically connected to each other, on the upper part thereof; a plurality of gold wires for electrically connecting the circuit pattern of the substrate and the edge pads of the first semiconductor chip, respectively; a second semiconductor chip having a plurality of center pads corresponding to those of the first semiconductor chip, the formative side being opposite to that of the first semiconductor chip; and a plurality of bumps interposed between the center pads of the first semiconductor chip and the center pads of the second semiconductor chip for joining and electrically connecting them.